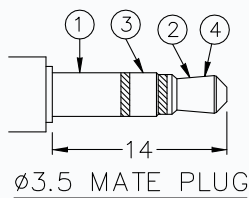
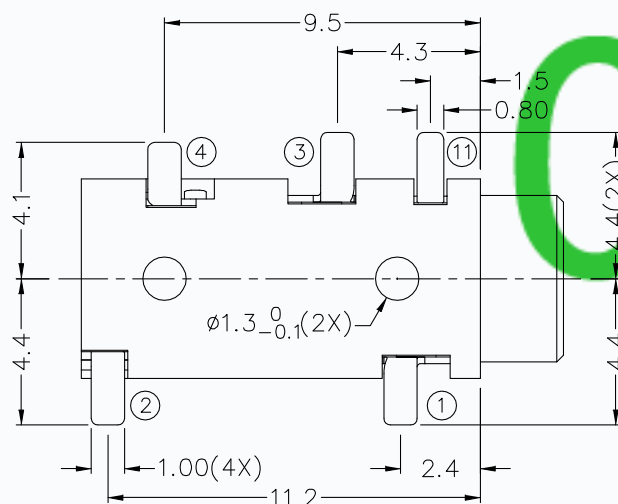
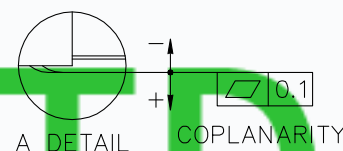
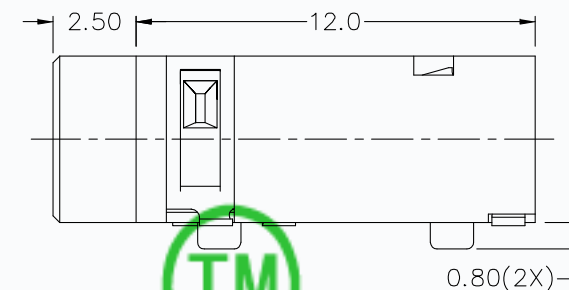
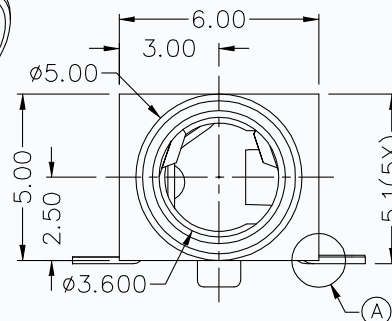
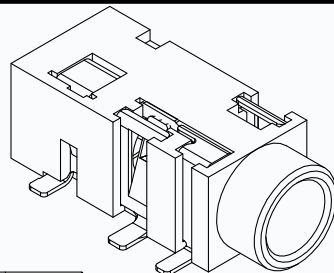
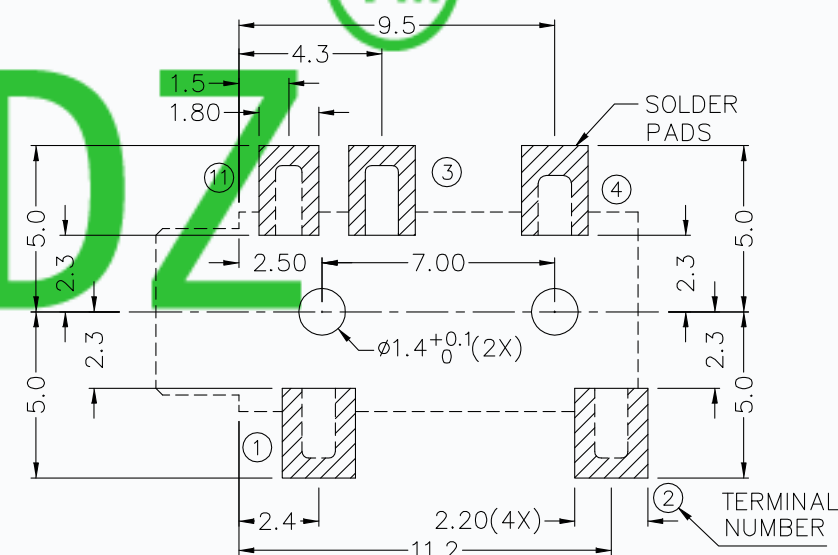


CAD FILE:



* MATERIAL

TERMINAL 1 : COPPER ALLOY
TERMINAL 2 : COPPER ALLOY
TERMINAL 3 : COPPER ALLOY
TERMINAL 4 : COPPER ALLOY
TERMINAL 11 : COPPER ALLOY
HOUSING : PA6T



RECOMMENDED
SOLDER PAD LAYOUT

MODEL NO.	T13-35045D	T13-35044D
SCHEMATIC		

TOLERANCE
UNLESS SPECIFIED
WITHIN 1.5mm : $\pm 0.1\text{mm}$
OVER 1.5mm : $\pm 0.2\text{mm}$

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DONGGUAN TIANDU ELECTRONICS CO., LTD.

TITLE : 3.5mm SMD PHONE JACK

UNIT : mm

DRWG NO.: CMTDDZ-T13-3504D-00

MODEL: T13-3504D

SCALE: 3:1

DWN. ERIC 2013-6-17

CMTDDZ 东莞市田都电子有限公司
DONGGUAN TIANDU ELECTRONICS CO.,LTD.

CHK'D MAIKO 2013-6-17

APPD. Coco 2013-6-17

APPD. DESCRIPTIONS OF REVISION